



Material Composition Declaration

EPC2100

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	23.0 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	19.9310	86.6376	89.2946	866376
	Silicon oxide	7631-86-9	0.0893	0.3881		3881
	Silicon nitride	12033-89-5	0.0318	0.1384		1384
	Gallium nitride	25617-97-4	0.1031	0.4481		4481
	Aluminum	7429-90-5	0.1567	0.6810		6810
	Aluminum nitride	24304-00-5	0.0248	0.1080		1080
	Titanium	7440-32-6	0.0046	0.0201		201
	Titanium nitride	25583-20-4	0.0150	0.0653		653
	Copper	7440-50-8	0.0052	0.0226		226
	Tungsten	7440-33-7	0.0076	0.0332		332
	Polyimide		0.1731	0.7523		7523
Under Bump Metal	Titanium	7440-32-6	0.0015	0.0065	0.5504	65
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1251	0.5439		5439
Solder Bump	Tin	7440-31-5	2.2310	9.6980	10.1550	96980
	Silver	7440-22-4	0.0934	0.4062		4062
	Copper	7440-50-8	0.0117	0.0508		508
Sum in total:			23.0050	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.